

STRESS-COMPENSATION LAYERS IN CONTACT ARRAYS,  
AND PROCESSES OF MAKING SAME

ABSTRACT OF THE DISCLOSURE

5           A stress-compensation layer is formed by pressing a solder bump into a  
compressible film within a mold chase. The stress-compensation layer flows  
against the solder bump and the compressible film such that at least a portion of the  
solder ball is embedded in the stress-compensation layer. The compressible film is  
removed to reveal at least a portion of the solder bump exposed and free of the  
10 stress-compensation layer. An article that exhibits a stress-compensation layer with  
a surface characteristic of the imposed flexible film is also included. A computing  
system that includes a stress-compensation layer with a surface characteristic of the  
imposed flexible film is also included.

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